Wire Wound Molded SMD Power Inductors
Size 5050

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▪ ℃
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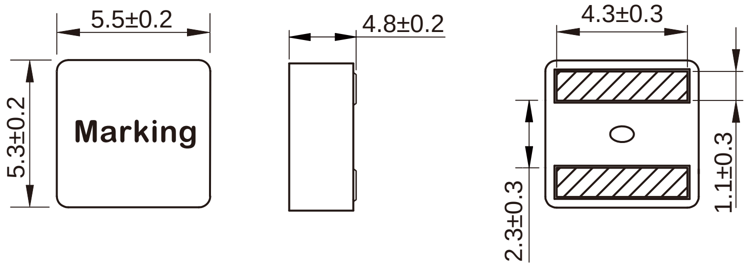
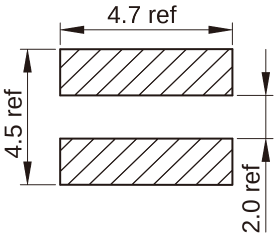
Dimensions: [mm]



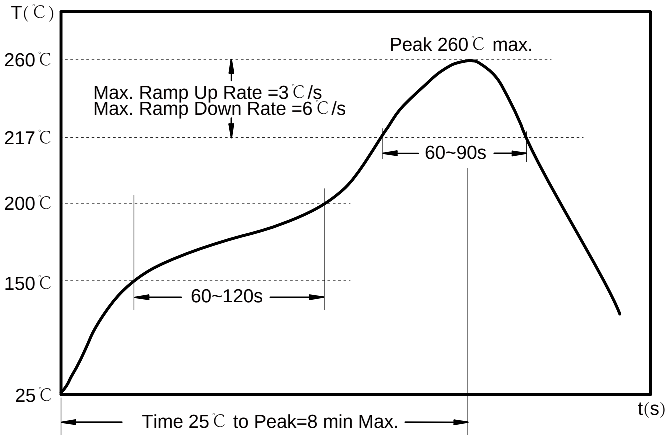
Land Pattern: [mm]



Electrical Properties:

Saturation Current will cause L to drop approximately 30%
Temperature Rise Current: The actual value of DC current when the temperature rise is △T=40°C

Soldering Reflow:



Preheat condition: 150 ~200℃/ 60~120 sec.

Allowed time above 217℃: 60~90 sec.

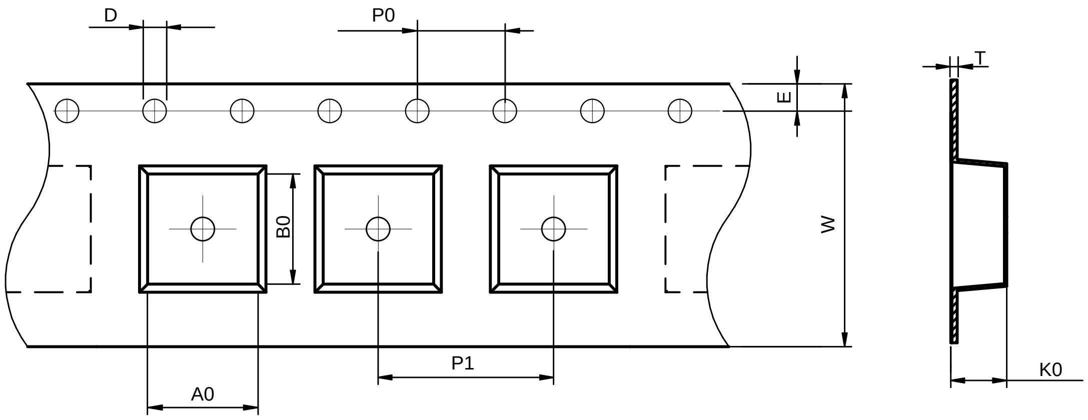
Max temperature: 260℃.

Max time at max temperature: 10 sec.

Allowed Reflow time: 2x max.

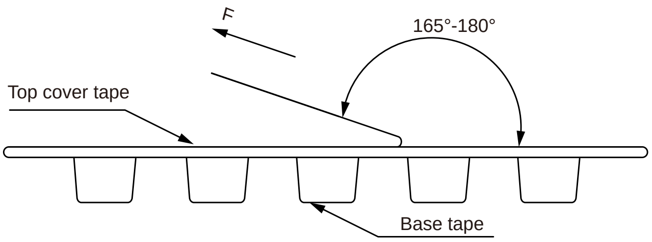
Packaging Information:

Tape Dimension:



Series	A0 (mm)	B0 (mm)	D (mm)	P0 (mm)	P1 (mm)	W (mm)	K0 (mm)	E (mm)	T (mm)
MDTE5050	6.0±0.1	5.7±0.1	1.5±0.1	4.0±0.1	8.0±0.1	16.0±0.3	5.3±0.1	1.75±0.1	0.35±0.05

Peel force of top cover tape:



The peel force of top cover tape shall be between 0.1 to 1.3 N

Product Marking:

Marking	Printing (Inductance)